

PCB Assembly Capability

Category	Description	Capability
File Formats	Gerber files(preferred), AutoCAD, DWG	274-X,274-D, DXF, ...
	BOM (Bill of Materials)	Excel(preferred), PDF
	Pick and Place file (XYRS)	X & Y coordinates
Board type	Board types for assembly	Rigid, Flexible, Rigid-Flex
Board Size	Minimum and Maximum	Smallest size: 2.0" x 2.0", 50mm x 50mm,Largest size: 19.7" x 19.7", 500mm x 500mm
Solder paste printing	Max stencil size	1560mm x 450mm
Pick and Place	Min. SMT part package	0201
	Min. IC pitch	0.3mm
	Min.chip size	01 005
	QFP lead pitch	0.38mm to 2.54mm
BGA capability	BGA ball pitch	0.5mm to 3.00 mm
	BGA ball size	0.4mm to 1.0mm
	Reballing and Rework (De-population and Re-population)	
Reflow	Optimized Reflow Profiling and multi-zone temperature control	
Wave flow	temperature control and tooling	
Assembly and builds	Press Fit Connectors	Yes
	Mechanical Assembly and Box Builds	Yes
	Cable & Harness Assembly	Yes
Rework	De-population and Re-population	Yes
	Fine Pitch	Yes
	Cuts & Jumps	Yes
	Minor PCB Repair	Yes
Wash	De-ionized Wash	Yes
Testing	Visual Inspection	Yes
	AOI (Automated Optical Inspection)	Yes
	ICT (In Circuit Test)	Yes
	X-Ray	Yes
	Functional Test	Yes
	Firmware loading	Yes